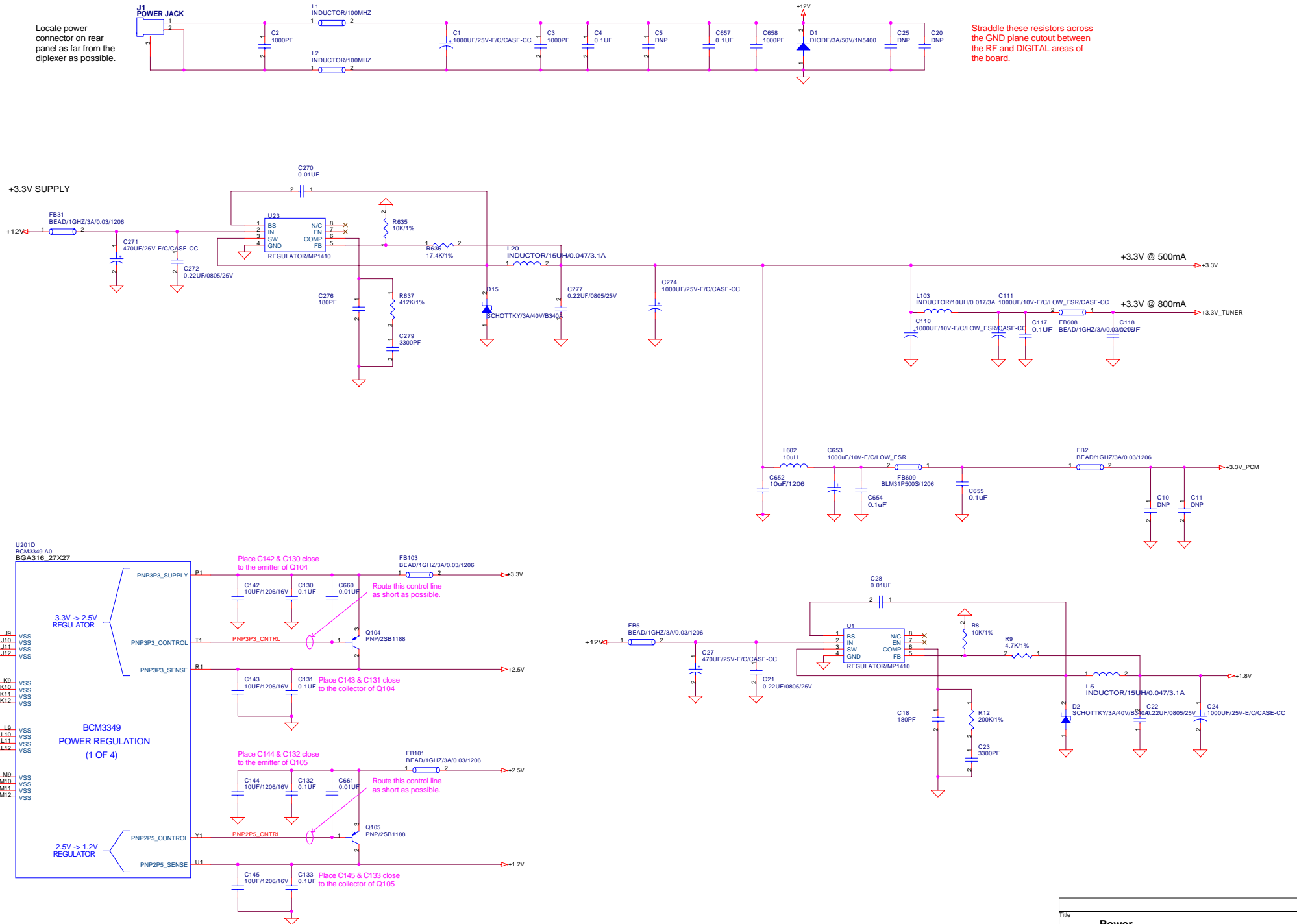


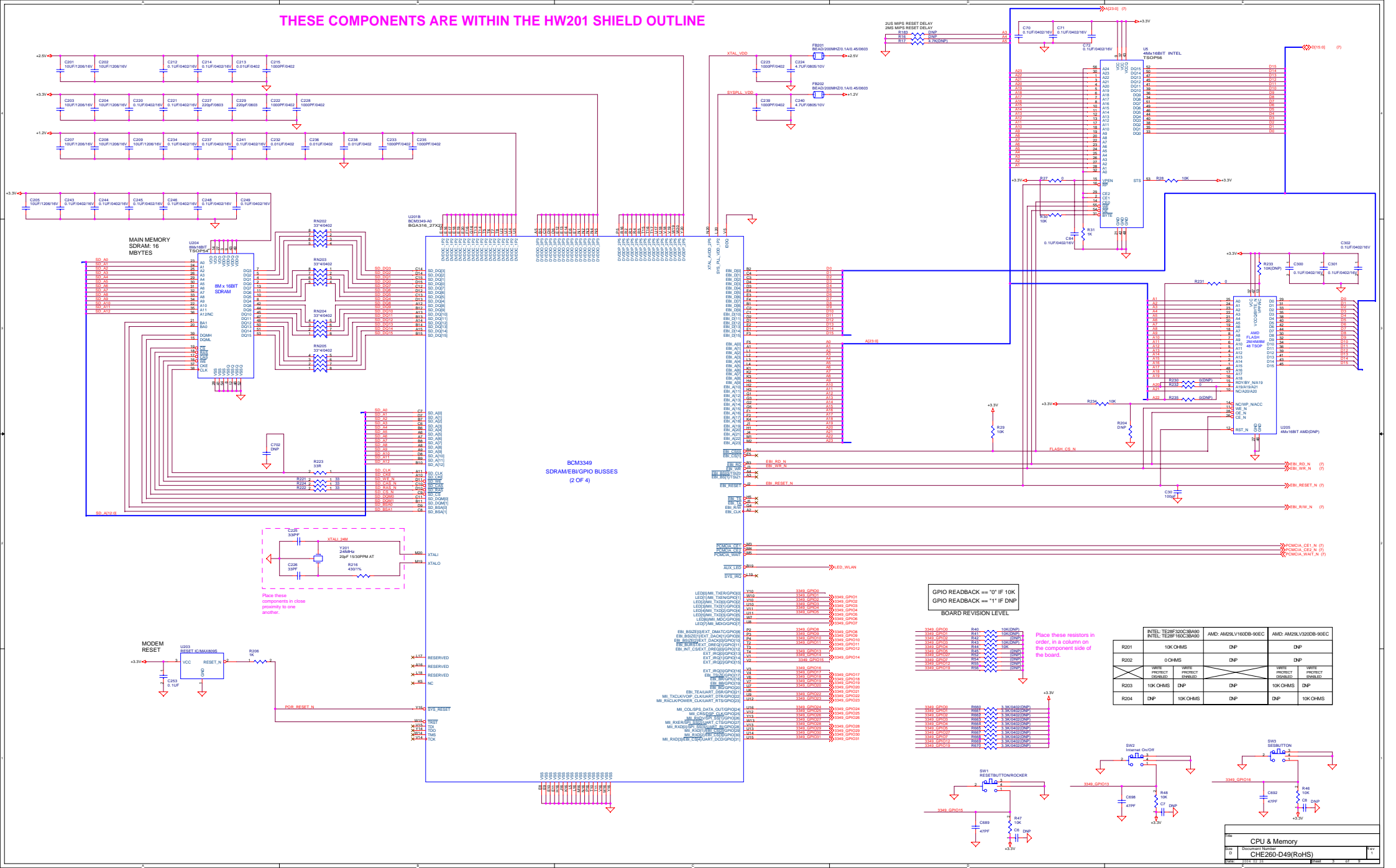
Locate power connector on rear panel as far from the diplexer as possible.

Straddle these resistors across the GND plane cutout between the RF and DIGITAL areas of the board.



Title		
Power		
Size	Document Number	Rev
C	CHE260-D49(RoHS)	1
Date:	2004 02 26	Sheet 2 of 8

THESE COMPONENTS ARE WITHIN THE HW201 SHIELD OUTLINE

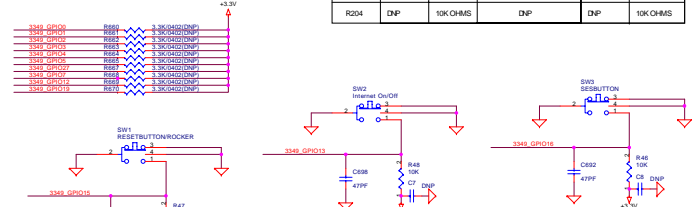


GPIO READBACK == "0" IF 10K
GPIO READBACK == "1" IF DNP

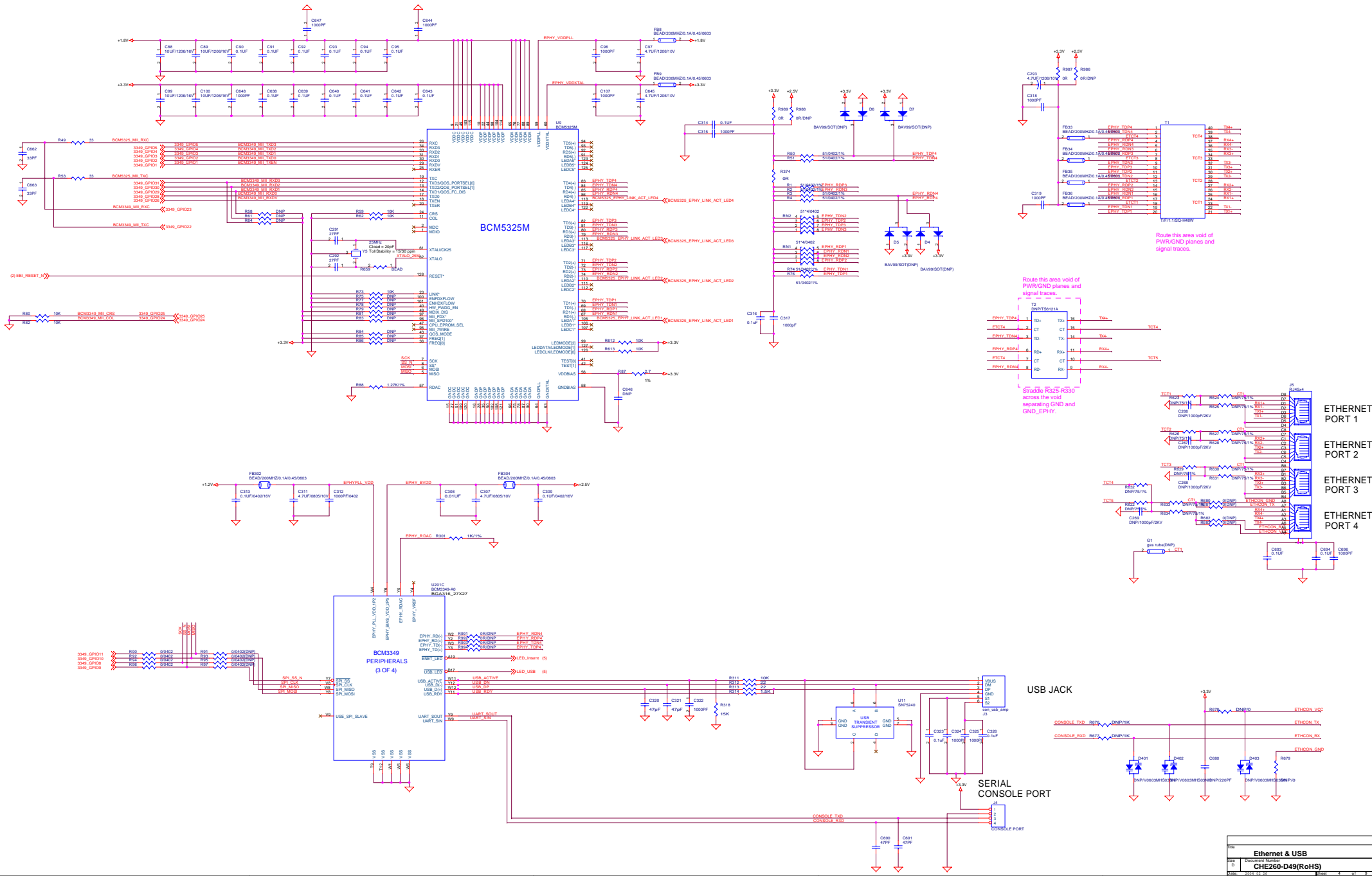
BOARD REVISION LEVEL

	INTEL T22B1602B160 INTEL T22B1602B160	AMD AM29LV160B-90EC	AMD AM29LV160B-90EC
R201	10K CHMS	DNP	DNP
R202	0 CHMS	DNP	DNP
R203	10K CHMS	DNP	10K CHMS
R204	DNP	10K CHMS	DNP

Place these resistors in order, in a column on the component side of the board.

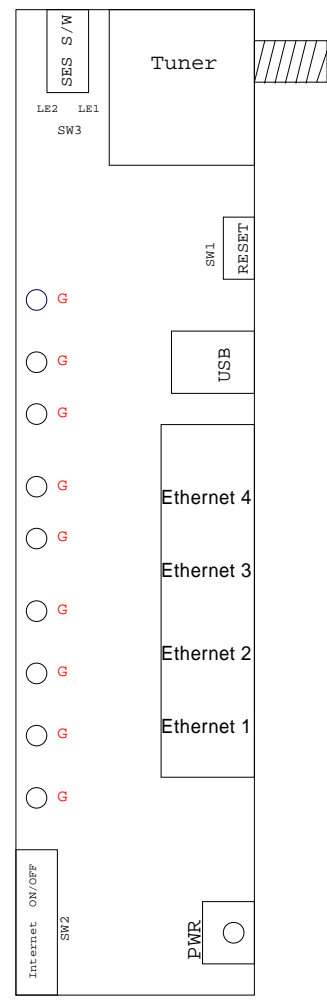
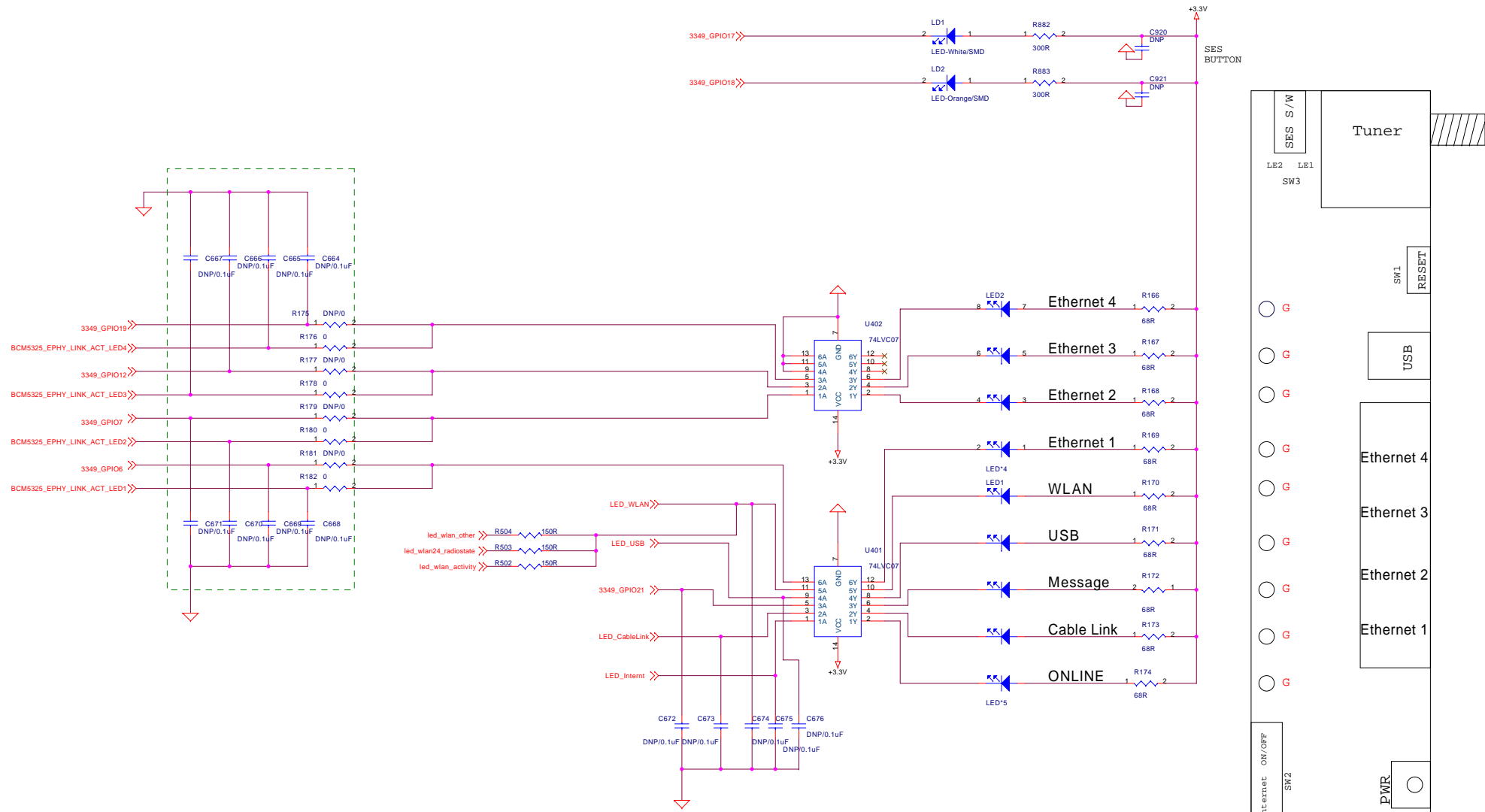


File	CPU & Memory
Board	CHE260-D49(RoHS)
Rev	01
Date	2011-11-21
Author	
Part	
Proj	
Sheet	01 of 01

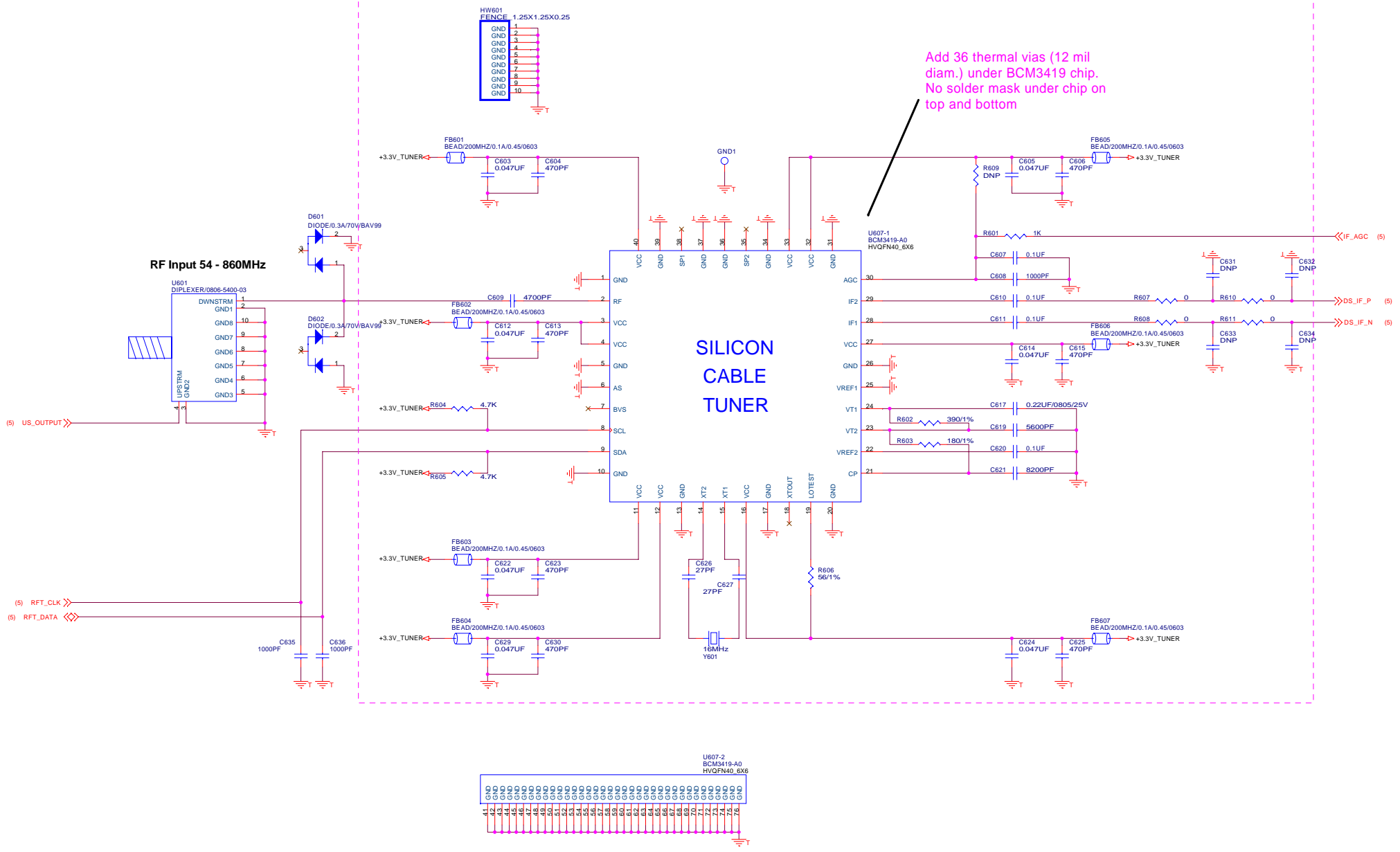


Rev	Changes	Date	By
1	Initial Release	2013-11-21	...

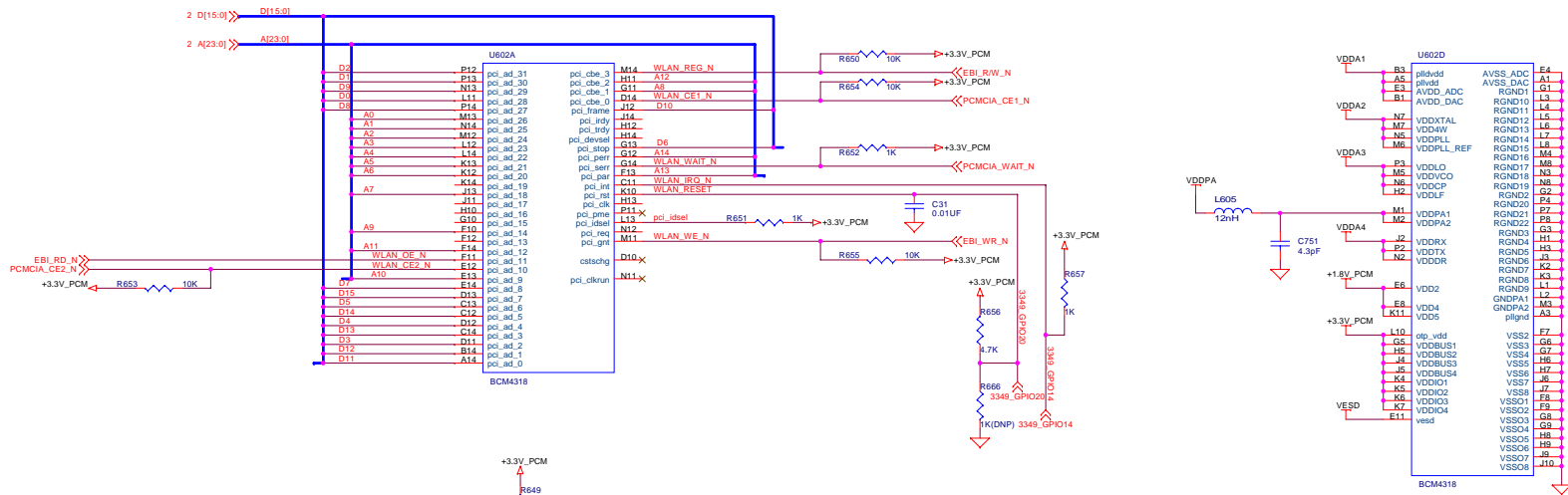
Ethernet & USB
CHE260-D49(RoHS)



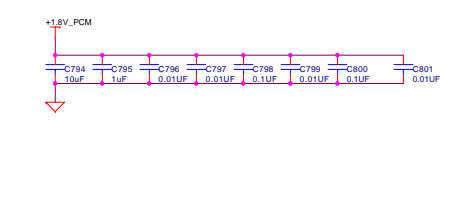
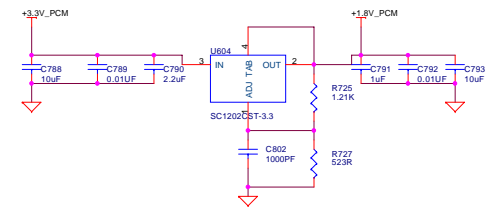
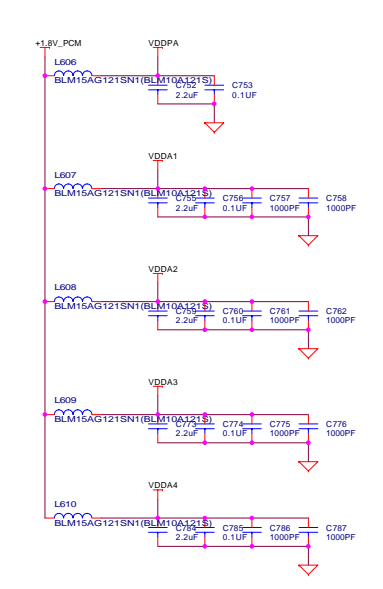
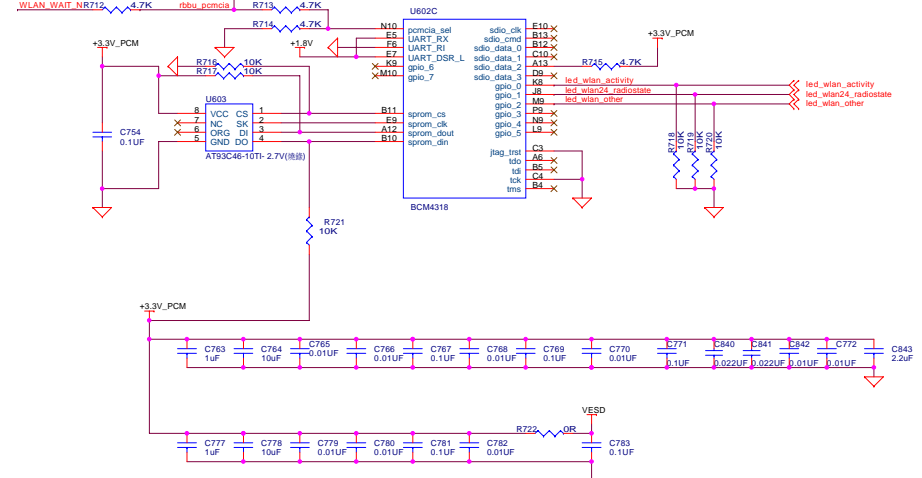
THESE COMPONENTS ARE WITHIN THE HW601 SHIELD OUTLINE

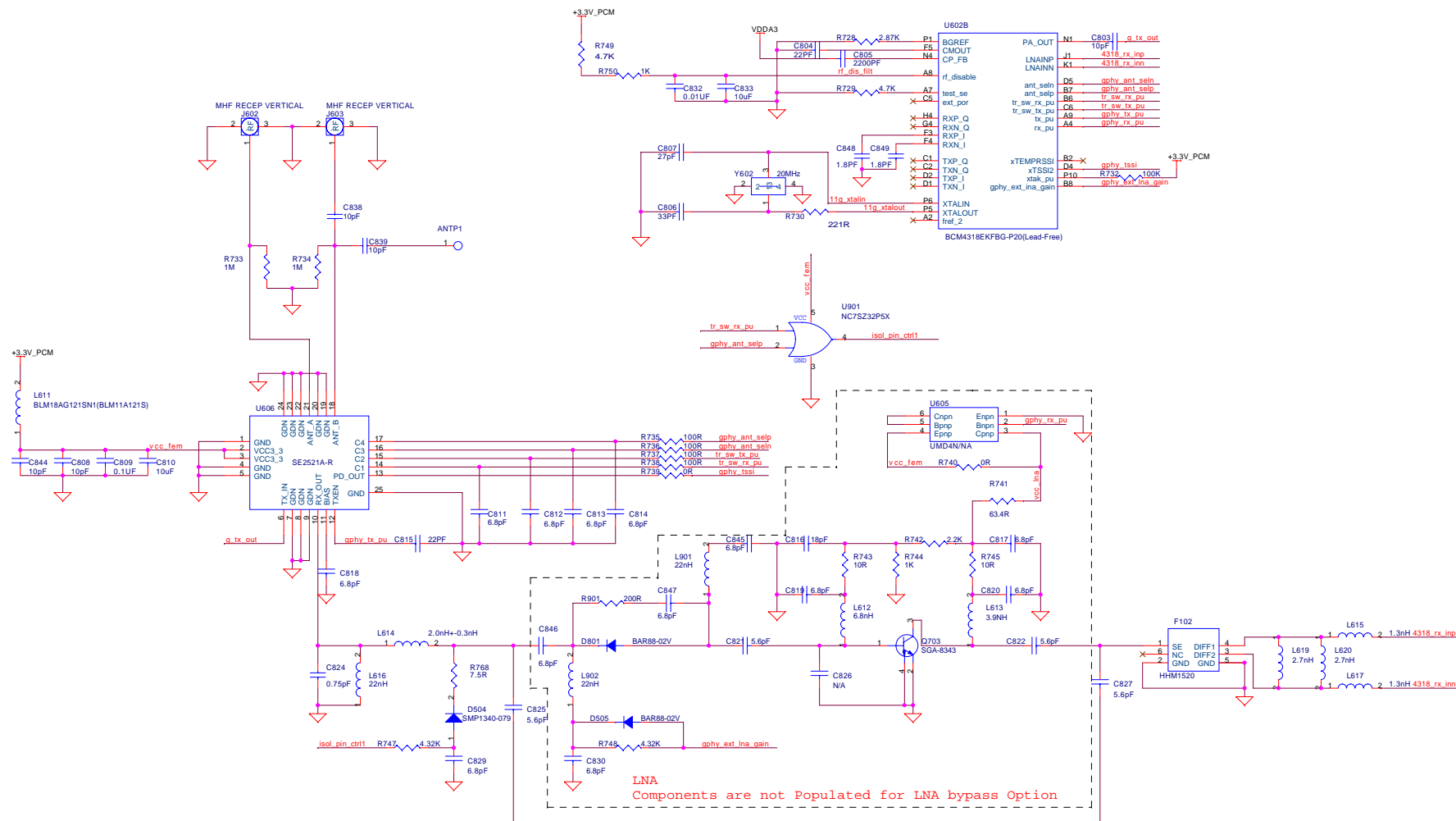


Add 36 thermal vias (12 mil diam.) under BCM3419 chip.
No solder mask under chip on top and bottom



	pcmcia	pci_serr	sdio_cmd
pci	0	x	1
cb	0	x	0
sdio	1	0	x
pcmcia	1	1	x





LNA
Components are not Populated for LNA bypass Option

Title		RF_FE	
Size	Document Number	CHE260-D49(RoHS)	
C			
Date:		Sheet	8 of 8
		Rev	1